

# Surface-Mount TMBS® (Trench MOS Barrier Schottky) Rectifier

## eSMP® Series



Top View

Bottom View

### SlimSAW (DO-221AD)

Cathode  Anode

## DESIGN SUPPORT TOOLS

[click logo to get started](#)


## PRIMARY CHARACTERISTICS

|                               |                    |
|-------------------------------|--------------------|
| $I_{F(AV)}$                   | 2 A                |
| $V_{RRM}$                     | 60 V               |
| $I_{FSM}$                     | 60 A               |
| $V_F$ at $I_F = 2$ A (125 °C) | 0.46 V             |
| $T_J$ max.                    | 175 °C             |
| Package                       | SlimSAW (DO-221AD) |
| Circuit configuration         | Single             |

## FEATURES

- Low-profile package
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
  - Automotive ordering code: base P/NHM3
- Compatible to SOD-128 package case outline
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

## MECHANICAL DATA

**Case:** SlimSAW (DO-221AD)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

**Polarity:** color band denotes cathode end

## MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)

| PARAMETER  | SYMBOL            | VSS8D2M6    | UNIT |
|--|-------------------|-------------|------|
| Device marking code  |                   | V2M6        |      |
| Maximum repetitive peak reverse voltage  | $V_{RRM}$         | 60          | V    |
| Maximum average forward rectified current (fig.1)                                  | $I_{F(AV)}^{(1)}$ | 2           | A    |
| Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load | $I_{FSM}$         | 60          | A    |
| Operating junction temperature range   | $T_J^{(3)}$       | -40 to +175 | °C   |
| Storage temperature range  | $T_{STG}$         | -55 to +175 |      |

## Notes

(1) Free air, mounted on recommended copper pad area

(2) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$



| ELECTRICAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted) |                       |                         |                               |      |      |      |
|--|-----------------------|-------------------------|-------------------------------|------|------|------|
| PARAMETER  | TEST CONDITIONS       |                         | SYMBOL                        | TYP. | MAX. | UNIT |
| Instantaneous forward voltage  | I <sub>F</sub> = 1 A  | T <sub>A</sub> = 25 °C  | V <sub>F</sub> <sup>(1)</sup> | 0.48 | -    | V    |
|  | I <sub>F</sub> = 2 A  |                         |                               | 0.54 | 0.62 |      |
|  | I <sub>F</sub> = 1 A  | T <sub>A</sub> = 125 °C |                               | 0.36 | -    |      |
|  | I <sub>F</sub> = 2 A  |                         |                               | 0.46 | 0.54 |      |
| Reverse current  | V <sub>R</sub> = 60 V | T <sub>A</sub> = 25 °C  | I <sub>R</sub> <sup>(2)</sup> | -    | 0.2  | mA   |
|  |                       | T <sub>A</sub> = 125 °C |                               | 1.5  | 5.0  |      |
| Typical junction capacitance   | 4.0 V, 1 MHz          |                         | C <sub>J</sub>                | 430  | -    | pF   |

**Notes**(1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle(2) Pulse test: pulse width  $\leq 5\text{ ms}$ 

| THERMAL CHARACTERISTICS ( $T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise specified) |                          |      |      |                      |
|--|--------------------------|------|------|----------------------|
| PARAMETER  | SYMBOL                   | TYP. | MAX. | UNIT                 |
| Typical thermal resistance   | $R_{\theta JA}^{(1)(2)}$ | 120  | 150  | $^{\circ}\text{C/W}$ |
|  | $R_{\theta JM}^{(3)}$    | 12   | 15   |                      |

**Notes**(1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ 

(2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint

(3) Thermal resistance junction-to-mount to follow JEDEC 51-14 transient dual interface test method (TDIM)

| ORDERING INFORMATION (Example) |                 |                        |               |                                    |
|--------------------------------|-----------------|------------------------|---------------|------------------------------------|
| PREFERRED P/N                  | UNIT WEIGHT (g) | PREFERRED PACKAGE CODE | BASE QUANTITY | DELIVERY MODE                      |
| VSS8D2M6-M3/H                  | 0.033           | H                      | 3500          | 7" diameter plastic tape and reel  |
| VSS8D2M6-M3/I                  | 0.033           | I                      | 14 000        | 13" diameter plastic tape and reel |
| VSS8D2M6HM3/H <sup>(1)</sup>   | 0.033           | H                      | 3500          | 7" diameter plastic tape and reel  |
| VSS8D2M6HM3/I <sup>(1)</sup>   | 0.033           | I                      | 14 000        | 13" diameter plastic tape and reel |

**Note**

(1) AEC-Q101 qualified

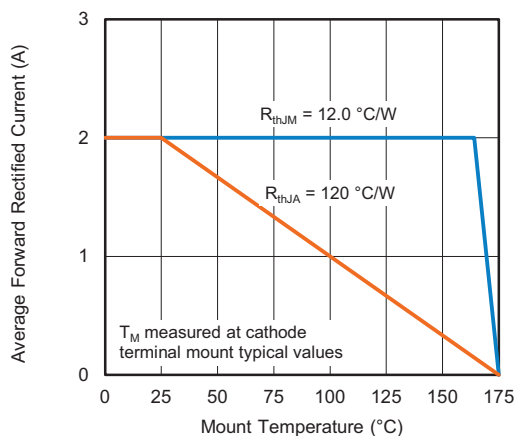
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

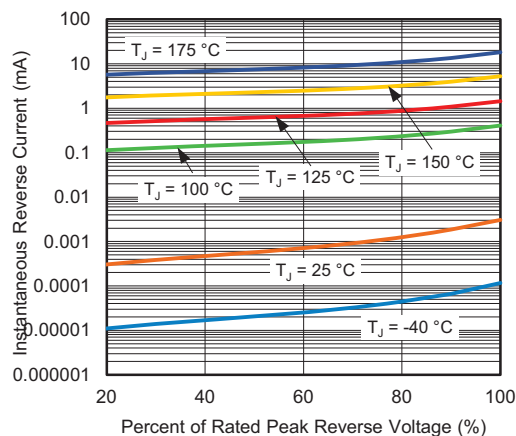


Fig. 4 - Typical Reverse Leakage Characteristics

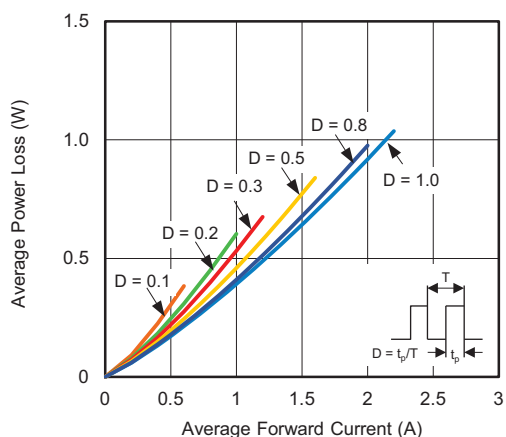


Fig. 2 - Forward Power Loss Characteristics

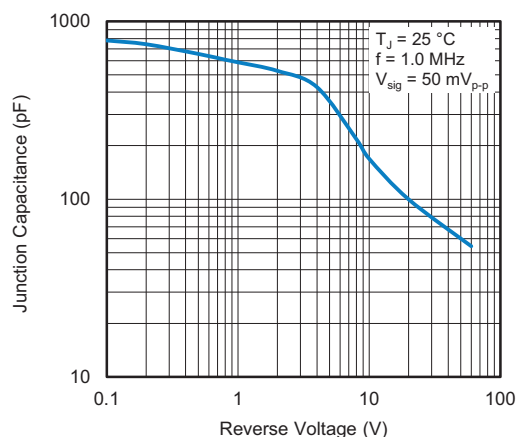


Fig. 5 - Typical Junction Capacitance

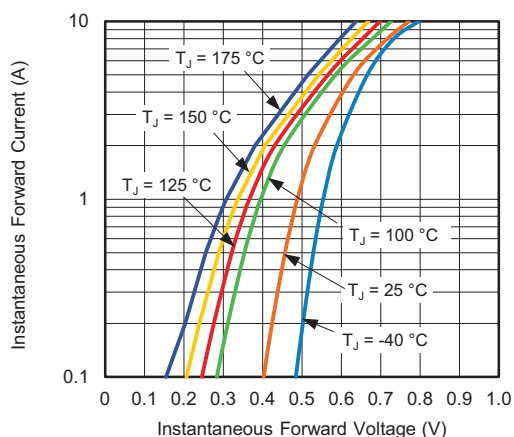


Fig. 3 - Typical Instantaneous Forward Characteristics

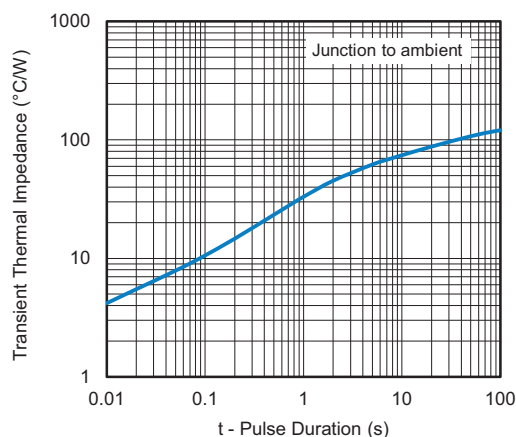
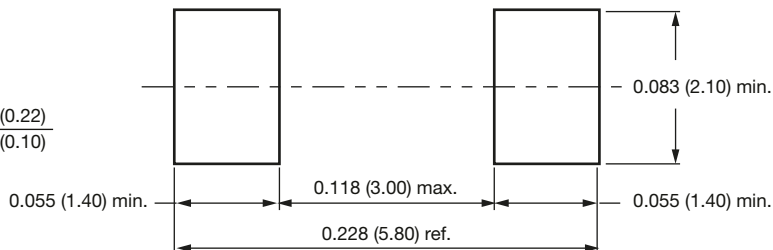
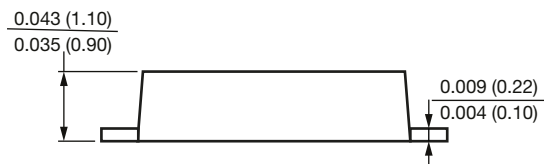
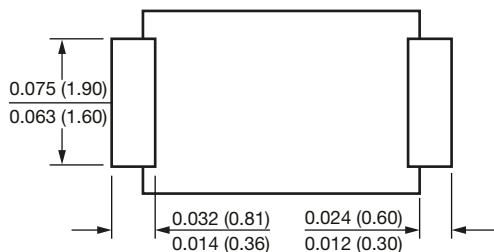
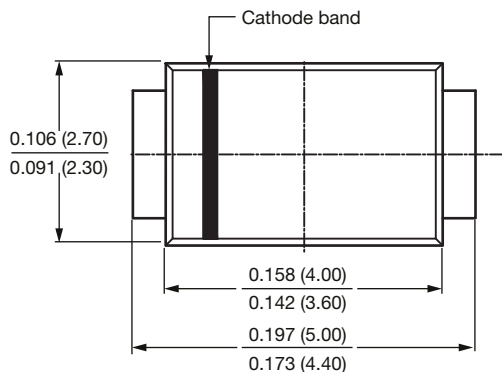


Fig. 6 - Typical Transient Thermal Impedance



**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)

**SlimSMAW (DO-221AD)**



**Mounting pad layout**



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